

L Number	Hits	Search Text	DB	Time stamp
8	1180	(tetramethylammo\$4 \$methlyammonium tetra\$ammonium) and ("CMP" "cmp" polish\$3)	USPAT	2003/01/16 14:52
9	34	(tetramethylammo\$4 \$methlyammonium tetra\$ammonium) and ("CMP" "cmp" polish\$3)	EPO; JPO; DERWENT; IBM_TDB	2003/01/16 14:53
10	293	(tetramethylammo\$4 \$methlyammonium tetra\$ammonium) and ("CMP" "cmp" polish\$3)	US-PGPUB	2003/01/16 14:53
11	2915	(polish\$3 "CMP" "cmp") and rough\$6 and (substrate wafer)	US-PGPUB	2003/01/16 14:58
12	11816	(polish\$3 "CMP" "cmp") and rough\$6 and (substrate wafer)	USPAT	2003/01/16 14:56
13	8421	((polish\$3 "CMP" "cmp") and rough\$6 and (substrate wafer)) and (rough\$6 same (substrate wafer layer film))	USPAT	2003/01/16 14:58
14	1675	(((polish\$3 "CMP" "cmp") and rough\$6 and (substrate wafer)) and (rough\$6 same (substrate wafer layer film))) and (rough\$6 adj2 (substrate wafer layer film))	USPAT	2003/01/16 14:58
15	2013	(polish\$3 "CMP" "cmp") and rough\$6 and (substrate wafer)	EPO; JPO; DERWENT; IBM_TDB	2003/01/16 14:59
16	1684	((polish\$3 "CMP" "cmp") and rough\$6 and (substrate wafer)) and (rough\$6 same (substrate wafer))	EPO; JPO; DERWENT; IBM_TDB	2003/01/16 15:00
-	0	hans-walitzki.in. howard-hogle.in. wing-luk.in. claudian-nicolesco.in.	USPAT	2003/01/16 13:41
-	0	hans-walitzki.in. howard-hogle.in. wing-luk.in. claudian-nicolesco.in.	US-PGPUB	2003/01/14 18:01
-	0	hans-walitzki.in. howard-hogle.in. wing-luk.in. claudian-nicolesco.in.	EPO; JPO; DERWENT; IBM_TDB	2003/01/14 18:01
-	517	438/690,691.ccls.	USPAT	2003/01/14 18:03
-	1379	438/692,693.ccls.	USPAT	2003/01/14 18:03
-	815	438/694,695.ccls.	USPAT	2003/01/14 18:03
-	569	438/697,699.ccls.	USPAT	2003/01/14 18:05
-	225	438/964.ccls.	USPAT	2003/01/14 18:06
-	288	438/974.ccls.	USPAT	2003/01/14 18:06
-	463	438/977.ccls.	USPAT	2003/01/14 18:07
-	428	438/459.ccls.	USPAT	2003/01/14 18:07
-	1108	438/460,464,465,455.ccls.	USPAT	2003/01/14 18:11

-	11149	(tetramethylammo\$4 \$methlyammonium tetra\$ammonium \$ammonium) and ("CMP" "cmp" polish\$3)	USPAT	2003/01/16 14:52
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Electron Devices Meeting, 1993. Technical Digest., International , 5-8 Dec 1993

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[\[Abstract\]](#) [\[PDF Full-Text \(284 KB\)\]](#) **IEEE CNF****2 Bonding of thin films on 200 mm silicon wafers using chemical mechanical polishing***Jones, E.C.; Tiwari, S.; Chan, K.K.; Solomon, P.M.; Power, M.;*

SOI Conference, 1998. Proceedings., 1998 IEEE International , 5-8 Oct 1998

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[\[Abstract\]](#) [\[PDF Full-Text \(296 KB\)\]](#) **IEEE CNF****3 Morphology and adhesion strength in electroless Cu metallized AlN substrate***Chang, J.H.; Duh, J.G.; Chiou, B.S.;*

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A Volume: 16 Issue: 8 , Dec 1993

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[\[Abstract\]](#) [\[PDF Full-Text \(812 KB\)\]](#) **IEEE JRN****4 Material removal mechanism in chemical mechanical polishing: theoretical modeling***Jianfeng Luo; Dornfeld, D.A.;*